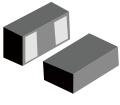


FEATURES

ESD protection for high speed data lines to IEC61000-4-2
ESD contact discharge typical 8KV, max 15KV
ESD air discharge typical 15KV, max 25KV
Surface mount
Extremely low capacitance
Very low leakage current
Fast response time
Bi-directional ESD protection
Lead free solder termination
The best ESD protection for high frequency, low voltage applications







Schematic Symbol

APPLICATIONS

I	High Definition	Multi-Media	Interface	(HDMI)
1	Ingri Demition	Mutti Mculu	michace	

- Digital Visual Interface (DVI)
- Display Port Interface (DP)
- Unified Display Interface (UDI)
- | Mobile Display Digital Interface (MDDI)
- Gigabit Ethernet
- USB2.0 and USB3.0
- IEEE1394 interface

CAUTION

This component is designed for signal line protection only, Not intended

to be used under bias, not for application with a power line.

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003





ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
-	Maximum Contact discharge voltage Per IEC61000-4-2	15KV	V
-	- Maximum Air discharge voltage Per IEC61000-4-2		V
T _{OPER} Maximum Operating temperature		-40 to +90	°C
T _{srg} Maximum Storage temperature		-55 to +125	°C
TL	Maximum lead temperature for soldering during 10s	260	°C

ELECTRICAL CHARACTERISTICS(T_A=25°C)

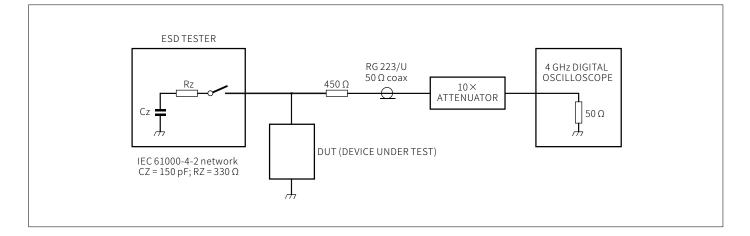
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _R	Rated Voltage	-	-	-	9	V
V _T	Trigger Voltage	IEC61000-4-28KV contact discharge	-	300	-	V
V _c	Clamping Voltage	IEC61000-4-28KV contact discharge	-	35	-	V
I _L	Leakage Current	DC 5V shall be applied on component	-	-	0.10	μΑ
C _P	Capacitance	$V_{R} = 0V, f = 1MHz$	-	0.05	-	рF

Note:

 $1\ensuremath{\smallsetminus}$ Trigger and clamping voltage are measured per IEC 61000-4-2, 8KV contact discharge method.

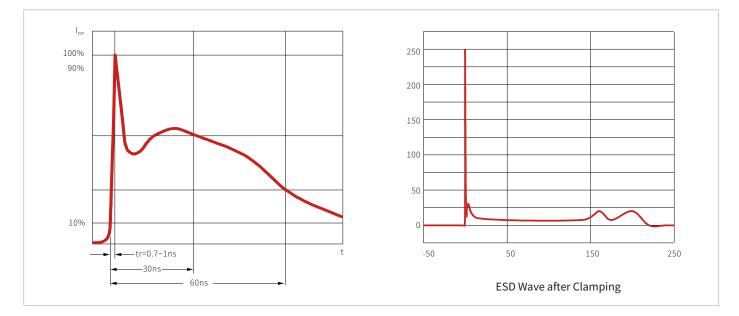
2. After reliability tests such as high temp storage, temp cycles, continuous ESD strike etc, the maximum leakage current is less than 10uA.

ESD CLAMPING TEST





CHARACTERISTIC CURVES

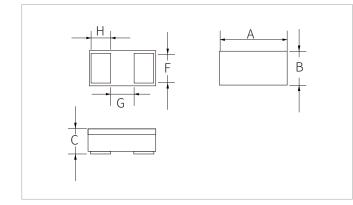


SOLDERING PARAMETERS

	Reflow Condition	Lead–free assembly
	Temperature Max (T _{s(min)})	150°C
Pre Heat	Temperature Max (T _{s(max)})	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ran	np up rate (Liquidus Temp (T_L) to peak	3°C/second max
	T _{s(max)} to T _L - Ramp-up Rate	3°C/second max
Reflow	Temperature (T _L) (Liquidus)	217°C
Rellow	Time (min to max) (t_L)	60 – 150 seconds
Peak Temp	erature (T _P)	260°C
Time within	n 5°C of actual peak Temperature (t _p)	20 – 40 seconds
Ramp-dow	n Rate	6°C/second max
Time 25°C t	to peak Temperature (T _P)	8 minutes max.
Do not exce	eed	260°C

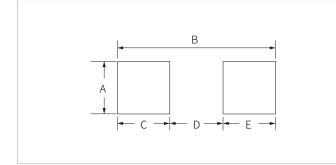


PACKAGE INFORMATION



Ref.		Dimensi	on		
iten	Min.	Тур.	Max.	Unit	
А	0.95	1.0	1.05		
В	0.45	0.50	0.55		
С	0.32	0.36	0.40	100.000	
Н	0.28	0.30	0.32	mm	
F	0.41	0.43	0.45		
G	0.32	0.34	0.36		

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Dimension	Unit
А	0.55	
В	1.05	
С	0.40	mm
D	0.25	
E	0.40	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SAE0402B9.0UA	0402	10000PCS	7"



Headquarters

No.3387 Shendu Road Pujiang I&E Park Minhang Shanghai China 201000

Hotline 400-021-5756

Web

Https://www.semiware.com

Tel: 86-21-3463-7458 Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001 Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654 Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172 Ext: 8868 Email: cs03@semiware.com

By QR Code





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